QuickSpecs

Overview

HPE Edgeline EL10 Intelligent Gateway Series



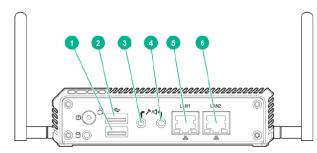
Is your company struggling with moving analytics to the edge of your network?

HPE Edgeline Gateways enable organizations to rapidly acquire, analyze and take action on real-time data as it's being collected for additional analysis at a later stage. Bringing computing and analytics close to the edge accelerates the speed of your decision making and reduces the chance of lost opportunities or a missed red flag. HPE Edgeline Gateways are a perfect complement to the industry's first HPE Edgeline Converged Edge Systems for expanding your Internet of Things (IoT) infrastructure beyond traditional data center confines and to enable true edge computing.

The HPE Edgeline EL10 Intelligent Gateway is an entry-level ruggedized compute solution designed for data aggregation and light analysis at the edge itself. It is optimally configured with CPU, memory, connectivity and an expansion I/O selection to address a host of IoT needs. HPE Edgeline Intelligent Gateways are designed to operate in harsh edge environments, such as such as manufacturing plants, oil and gas facilities and power stations, where wide operating temperature ranges, tolerance for high levels of shock/vibration and resilience against ingress are the norm. These gateways are complete solutions out-of-the-box, designed to be easy-to-use and quick-to-deploy. A universal power kit and a range of mounting kits allow these systems to be placed in a wide range of locations

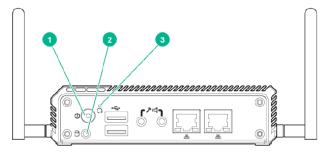


Overview



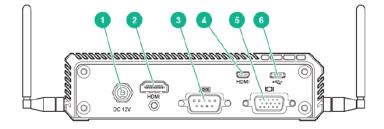
Front Panel Components

- 1. USB 2.0 connector
- 2. USB 3.0 connector
- 3. Audio In
- 4. Audio Out
- 5. LAN 1 connector (10/100/1000 Mbps)
- 6. LAN 2 connector (10/100/1000 Mbps)



Front Panel LEDs and Buttons

- 1. Power On/Off Button & LED
- 2. Drive LED
- 3. Reset Button (indented)



Rear Panel Components

- 1. Power connector
- 2. HDMI connector
- 3. Serial port connector (RS-232 or RS-422/485)
- 4. Micro-HDMI connector
- 5. VGA connector
- 6. Micro USB 2.0 connector

Key features of HPE Edgeline Intelligent Gateways

- Purpose Built: HPE Edgeline Intelligent Gateways are ruggedized compute solutions designed to operate in a variety of edge environments Industrial, Manufacturing, Smart Infrastructure, Oil & Gas etc.
- Optimum Configuration: Optimum CPU, memory, connectivity and expansive I/O selection addresses a host of IoT needs. Designed for Future Capabilities: Product designed to support a host of modular connectivity options that are customer upgradeable providing a strong foundation for future growth.
- Secure Platform: I /O Port Disablement, BIOS Password , Secure Boot. HPE Aruba software such as ClearPass to authenticate edge devices and secure VPN to protect remote connections
- Industrial Grade: Extended operating temperature -20°C to 60°C, Passively cooled, Shock and Vibration Tested, IP40 Certified
- Complete Solution: Easy-to-use and quick-to-deploy including a universal power kit (USA, UK, EURO and JPN) as well as universal mounting kit in support of DIN and wall mount applications.

The HPE Edgeline EL10 Intelligent Gateway offers the following unique benefits:

- Rugged price/performance-optimized edge gateway designed for entry level deployments
- Optimally configured with an Intel Atom CPU, 4GB RAM, 32 GB SDD Storage and an expansive I/O selection .
- Low power solution: 12 Volts DC with locking connector (typical total power consumption of 10.5 Watts)
- Designed for Future Capabilities: 2 mini-PCIe card slots enable a host of connectivity options that are customer upgradeable providing a strong foundation for future growth requirements.

| Processor | Intel® Atom™ Model | SoC HFM Frequency | SoC LFM Frequency | Cores | L2 Cache | Power | DDR3 MHz |
|-----------------------------|---|----------------------|------------------------------|----------------------------|--------------------|--|----------------------|
| | E3826 | 1.46 GHz | 533 MHz | 2 | 1 MB | 7W | 1067 |
| | NOTE: For more | information reg | arding Intel® | Atom, plea | ise see the follo | wina URL: | |
| | NOTE: For more information regarding Intel [®] Atom, please see the following URL: http://www.intel.com/content/www/us/en/processors/atom/atom-processor.html | | | | | | <u>r.html</u> |
| Chipset | Integrated with S | SoC | | | | | |
| Graphics | Intel® HD Graphics (integrated with SoC) Base: 533 MHz Burst: 667 MHz | | | | | | |
| Memory | Туре | DDR3 Si | DDR3 Small-Outline (SO-DIMM) | | | | |
| | Supported DIMMs | | | DDR3L-1067 4GB (1R x 8) | | | |
| | DIMM Slots Available | | | | | rs per processor, 1 channels per DIMMs per channel) | |
| | Maximum Capa | acity (SO-DIMM) |) / | чGB | | (1 x 4GB SO-D | MM) |
| | NOTES: | | | | 1 | | |
| Expansion slots | The SoC supports 2 memory channels but a DIMM slot is available on only 1 channel Only 4GB SO-DIMMs are currently offered with this model, but it's compatible with 2GB/8GB SO-DIMMS. Registered DIMMs (RDIMMs), Load Reduced DIMMs (LRDIMMs) and Non-Volatile DIMMs (NVDIMMs) are not supported. One (1) Half-size mini-PCle Expansion Slot – Slot #2 | | | | | | |
| Network | One (1) Full-size mini-PCIe Expansion Slot – Slot #1. Can also be used for mSATA NOTE: This system model is pre-wired with 4 antenna attach points for use with wireless module options. Intel® i210AT - One (1) 10/100/1000Mbps Ethernet Port | | | | | | |
| Controller | Realtek 8111G – One (1) 10/100/1000Mbps Ethernet Port NOTE: This system model does not support Power-over-Ethernet (PoE). | | | | | | |
| Storage Controller | SATA controllers | are Integrated | in the Intel® A | tom [™] SoC | | | |
| and Devices | Slot # | Technology | y Bus V | Vidth | Connector Width | Form Factor | Supported Sizes |
| | SFF Drive Bay | SATA-2 | X | 1 | ×1 | 2.5" SFF | 32 GB |
| | mSATA Slot (shared with slot #1) | SATA-2 | X | 1 | x1 | mSATA | N/A (Third-party) |
| | NOTE: The SFF | drive in this sys | tem model is | not hot-sw | appable. | | |
| Maximum Internal | Drive Bay | | 32 GB | | 1 x 32 GB | | |
| Storage | mSATA Slot | | N/ | N/A (Third Party) | | - | |
| | NOTE: This syst offered. | em is compatib | le with any SI | FF or mSAT | A drive, but onl | y selected SSD | s are currently |
| Power Supply System Fans | External AC 36W None. Passively o | | - | supply kit (U | SA, UK, EURO a | ind JPN) | |

| Interfaces | One (1) RS-232 Serial Port – switchable to RS-422/485 4-wire by internal ribbon cable changes Two (2) USB 2.0 Ports – 1 standard and 1 micro One (1) USB 3.0 Port One (1) VGA Port – supports 2560 x 1600 @ 60 Hz Two (2) HDMI Port – 1 standard and 1 micro, supporting 1920 x 1080 @ 60 Hz One (1) Audio In and One (1) Audio Out |
|-----------------------------|---|
| | Power On/Off Button & LED Drive LED System Reset Button |
| Operating System Support | Four (4) pre-wired antenna attach points for wireless module options <u>Microsoft Windows IoT Core</u> <u>Microsoft Windows Server</u> <u>Canonical Ubuntu Snappy Core</u> <u>CentOS</u> |
| Industry Standard | NOTE: For more information on Hewlett Packard Enterprise's Certified and Supported systems for each OS and latest listing of software drivers available for your system, please visit our OS Support Site at: http://www.hp.com/go/ossupport and our driver download page which can be found from the HPE Support Center: http://www.hpe.com/support Microsoft® Logo certifications |
| Compliance | USB 2.0 and 3.0 Support ACPI 2.0 Compliant |
| | International/Ingress Protection (IP): IP40 Certified NOTE: IP40 – protected against ingress of objects such as tools and small wires >1mm, but not liquids. |
| Security | I/O Port Disablement BIOS Password UEFI Secure Boot HPE Aruba Secure VPN (for protecting remote connections) HPE Aruba ClearPass (for authenticating edge devices) |
| Trusted Platform Module | Trusted Platform Module 1.2 (Infineon SLB9635) is embedded on the system, and can be enabled and disabled using the BIOS NOTE: The TPM (Trusted Platform Module) is a microcontroller chip that can securely store artifacts used to authenticate the system. These artifacts can include passwords, certificates and encryption keys. Windows® BitLocker™ Drive Encryption (BitLocker) is a data protection feature available in Windows Server® 2008, 2012/2012 R2. BitLocker leverages the enhanced security capabilities of a Trusted Platform Module (TPM) version 2.0. The TPM works with BitLocker to help protect user data and to ensure that a server running Windows Server has not been tampered with while the system was offline. For more information about TPM, including a white paper, go to: https://www.hpe.com/h20195/v2/gethtml.aspx?docname=c04939549 NOTE: The TPM key is unique to every TPM deployed system and must be retained. Misplacing or losing the key could result in data loss. |
| Form Factor | HPE Edgeline EL10 Intelligent Gateway is a standalone product. Universal mounting kit allows for wall or DIN rail mounting. Optional VESA kit is available. |
| Warranty | This product is covered by a global limited warranty and supported by Hewlett Packard Enterprise Services and a worldwide network of Hewlett Packard Enterprise Authorized Channel Partners resellers. Hardware diagnostic support and repair is available for three years from date of purchase. Support for initial setup is available for 90 days from date of purchase. Enhancements to warranty services are available through customized service agreements. |
| | NOTE: System Warranty includes 3-Year Parts, 0-Year Labor, 0-Year Onsite support with next business day response. Additional information regarding worldwide limited warranty and technical support is |

available at: http://h20564.www2.hpe.com/hpsc/wc/public/home

Technical Specifications

NOTE:

This section lists some of the steps required to configure a Factory Integrated Model. To ensure only valid configurations are ordered, Hewlett Packard Enterprise recommends the use of a Hewlett Packard Enterprise approved configurator. Contact your local sales representative for information on configurable product offerings and requirements.

Step 1: Base Configuration (Choose System)

| HPE Edgeline Gateway | HPE Edgeline EL10 Intel Atom Dual Core 1.46GHz 4GB 32GB w/o Operating System | 847976-B21 |
|----------------------|--|------------|
| System | Intelligent Gateway | |

Step 2: Choose Factory Integration Options

| Connectivity Modules (Min:0, Max:1) | HPE Edgeline Wide Temperature Wi-Fi Option Kit NOTES: | 845779-B21 |
|--|--|------------|
| | Full-size mini-PCIe Card (FMC) with PCIe interface to system | |
| | Supports wide operating temperature of -20°C to 60°C | |
| | • Wi-Fi Module supporting 802.11 a/b/g/n, 2.4/5.0 GHz, and 2x2 MIMO with dual-antennas. Speeds up to 300 Mbps. | |
| | HPE Edgeline Wide Temperature WAN 3G Option Kit | 845788-B21 |
| | NOTES: | |
| | Full-size mini-PCIe Card (FMC) with USB 2.0 interface to system | |
| | SIM slot is located on the underside of the module | |
| | Supports wide operating temperature of -20°C to 60°C | |
| | • 3G/3.75G (HSPA+) WAN module supporting dual antennas. Speeds up to 21.0 Mbps Download and 5.76 Mbps Upload. | |
| | Supported frequencies: GSM GPRS EDGE: 850, 900, 1800, 1900 MHz, UMTS HSPA: 800 / 850*, 900, AWS 1700,1900, 2100 MHz, * includes Bands B6 and B19 (800 MHz) as a subset of B5 (850 MHz) | |
| Stop 7. Chaosa Ad | | |
| Step 3: Choose Ad NOTE: Some options ma | ay not be integrated at the factory. | |

Mounting Accessories HPE Edgeline EL10 Intelligent Gateway VESA Mounting Kit

848461-B21

Technical Specifications

HPE Edgeline EL10 Intelligent Gateway Chassis Dimensions

| Chassis Dimensions (H x W x D) | Aluminum Housing 35.98 mm (1.4") x 138.5 mm (5.5") x 116.4 mm (4.6") | | |
|-----------------------------------|---|--|--|
| Weight Power | 0.68 KG (1.5 lbs) Typical: 5.9W Maximum: 10.6W | | |
| Shock and Vibration | Operational Shock Operational Vibration NOTE: Shock and Vibra | 30 G, IEC 60068-2-27, half sine, 11 ms duration 3 Grms, IEC 60068-2-64, random, 5 ~ 500 Hz, 1 hr/axis ation testing conducted on a system configured with SSDs | |
| System Inlet Temperature | Extended Operating Non-Operating | -20° to 60°C (-4° to 140°F) at sea level NOTE: Operating temperature range can be reduced if any non-wide temperature options are configured in the system. -40° to 60°C (-40° to 140°F) | |
| Relative Humidify | Operating Non-Operating | 5 to 95% relative humidify (Rh), 40°C (104°F) maximum wet bulb temperature, non-condensing 5 to 95% relative humidify (Rh), 40°C (104°F) maximum wet bulb temperature, non-condensing | |
| Acoustic Noise | None - Passively coole | d solution with solid state drives | |
| Emissions Classification (EMC) | | Class B CE/FCC Class B (w/o RF) with base model only CE/FCC Class B (RF), PTCRB, GCF with Intel AC7260 WIFI Card and Telite HE910G 3G module nance to cited product specifications is based on sample (type) testing, ent. This product or family of products is eligible to bear the appropriate tatements. | |
| | | | |

Summary of Changes

| Date | Version History | Action | Description of Change |
|-------------|----------------------|---------|--|
| 16-Dec-2016 | From version 4 to 5 | Update | Comprehensive updates to introduction, features and ordering |
| | | | menus |
| 10-Jun-2016 | Froim version 3 to 4 | Update | Updates overall QuickSpecs information |
| 22-Jan-2016 | From version 2 to 3 | Update | Update the overview and technical specifications section |
| 11-Dec-2015 | From version 1 to 2 | Update | Update messaging for the HPE Edgeline EL10 Intelligent Gateway |
| | | | Series |
| 1-Dec-2015 | Version 1 | Created | Create the QS for the HPE Edgeline EL10 Intelligent Gateway Series |





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For hard drives, 1GB = 1 billion bytes. Actual formatted capacity is less.

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